



#9A
12-21-2
Roberts.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sehat Sutardja
Serial No. : 09/966,914
Filed : September 27, 2001
Title : IMPROVED INTEGRATED CHIP PACKAGE HAVING INTERMEDIATE SUBSTRATE

Art Unit : 2826
Examiner : Alexander Williams

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CERTIFICATE OF MAILING

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Date:

11/20/02

Suzanne M. Forno

Suzanne M. Forno

Commissioner for Patents
Washington, D.C. 20231

RESPONSE

In response to the action mailed July 31, 2002, please
amend the application as follows:

In the Claims:

Claims 1, 13, and 22 have been amended as follows:

- AI
1. (Amended) An integrated chip package, comprising:
at least one semiconductor chip having a first surface and
a second surface;
an intermediate substrate electrically coupled via
conductive bumps to the first surface of the at least one
semiconductor chip;